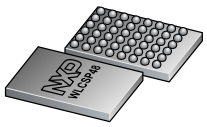

SOT1887-2

WLCSP48, wafer level chip-scale package; 48 bumps; 0.4 mm pitch, 2.51 mm x 3.55 mm x 0.5 mm body

11 January 2018 **Package information**

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	WLCSP48
Package type industry code	WLCSP48
Package style descriptive code	WLCSP (wafer level chip-size package)
Mounting method type	S (surface mount)
Issue date	11-12-2017
Manufacturer package code	98ASA01162D

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		-	-	2.51	-	mm
E	package width		-	-	3.55	-	mm
A	seated height		-	-	0.5	-	mm
e	nominal pitch		-	-	0.4	-	mm
n_2	actual quantity of termination		-	-	48	-	A/A

WLCSP48, wafer level chip-scale package; 48 bumps; 0.4 mm pitch, 2.51 mm x 3.55 mm x 0.5 mm body

2. Package outline

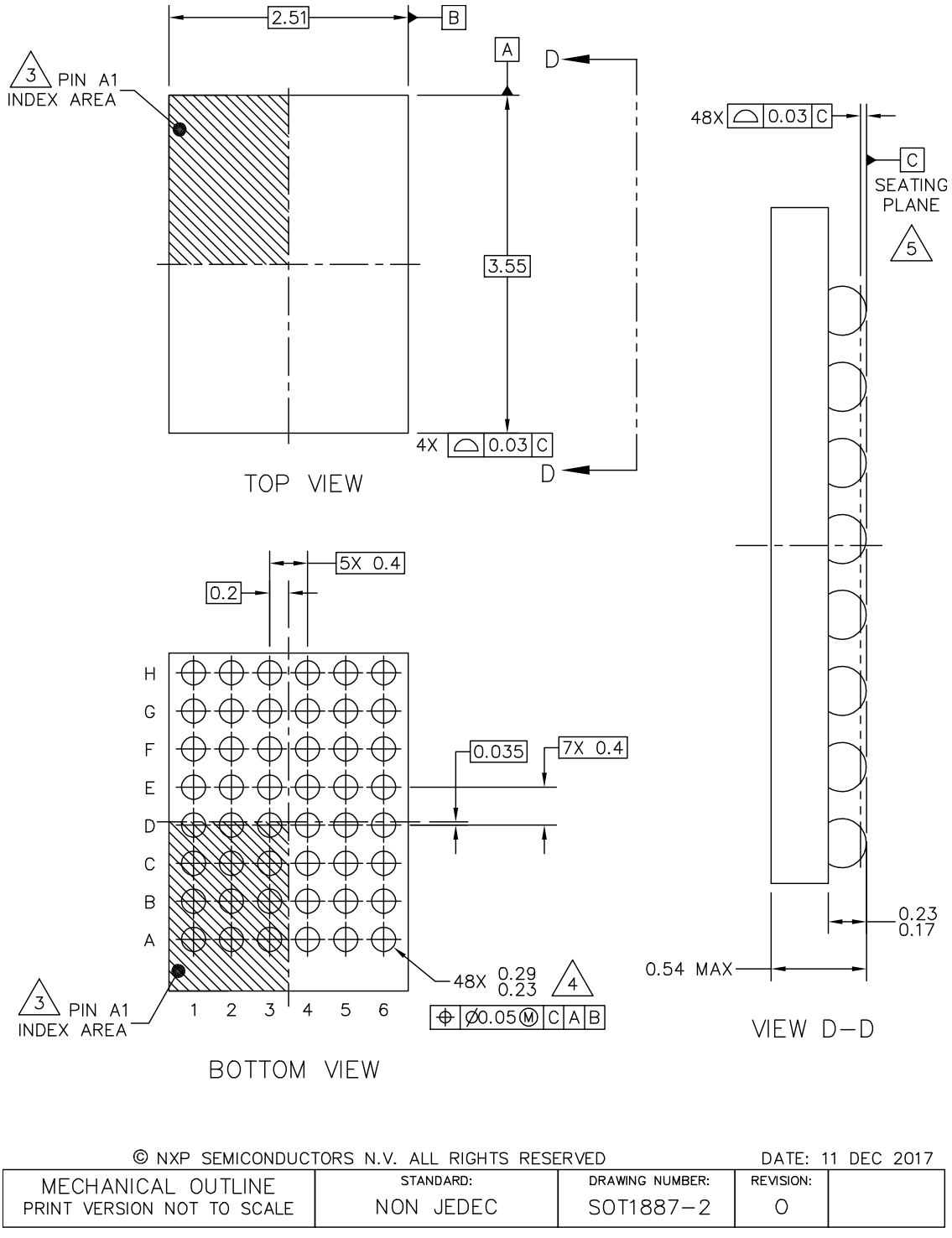

Fig. 1. Package outline WLCSP48 (SOT1887-2)

WLCSP48, wafer level chip-scale package; 48 bumps; 0.4 mm pitch, 2.51 mm x 3.55 mm x 0.5 mm body

Fig. 2. Package outline note WLCSP48 (SOT1887-2)

3. Soldering

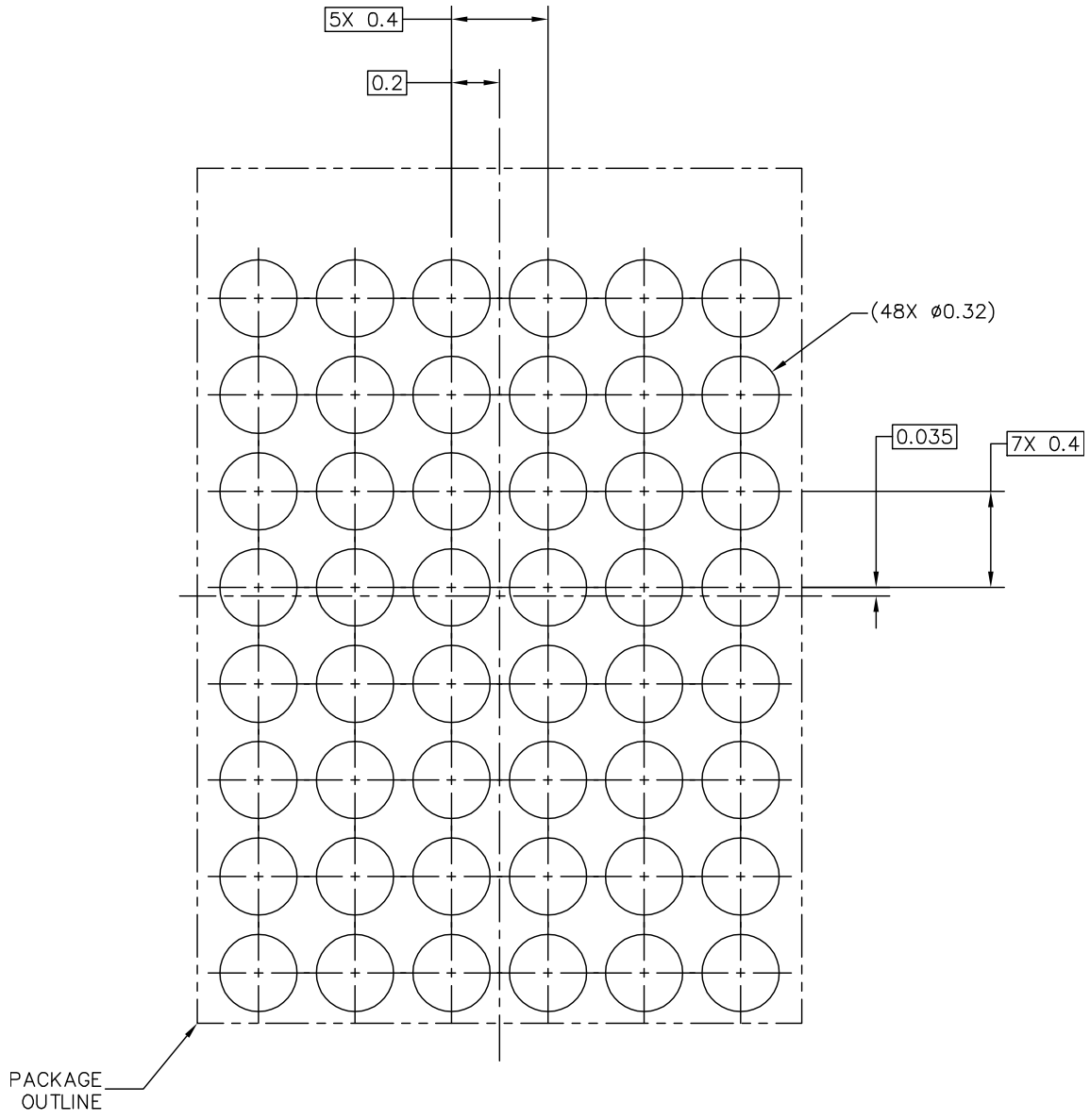

Fig. 3. Reflow soldering footprint for WLCSP48 (SOT1887-2)

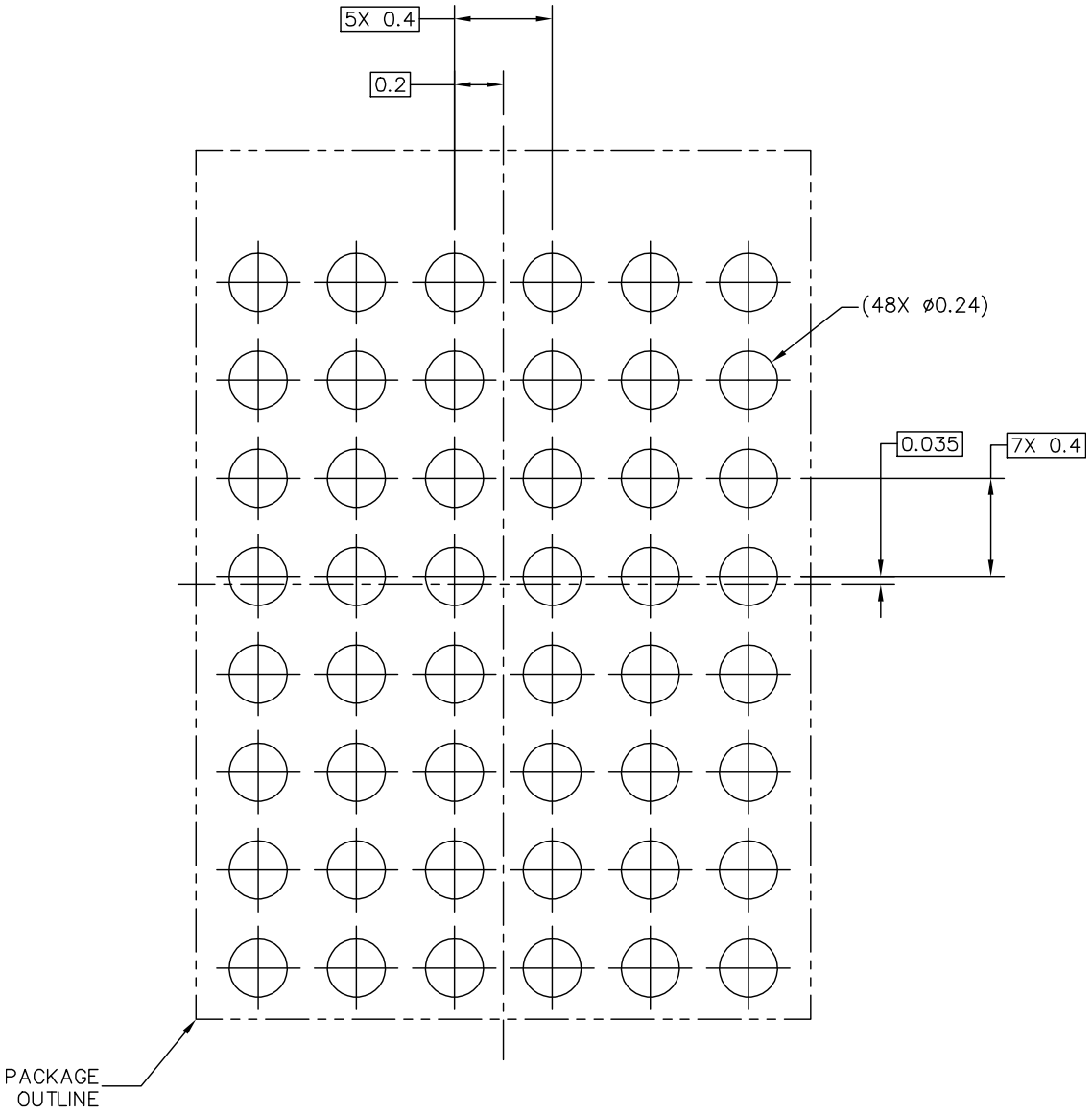

Fig. 4. Reflow soldering footprint part2 for WLCSP48 (SOT1887-2)

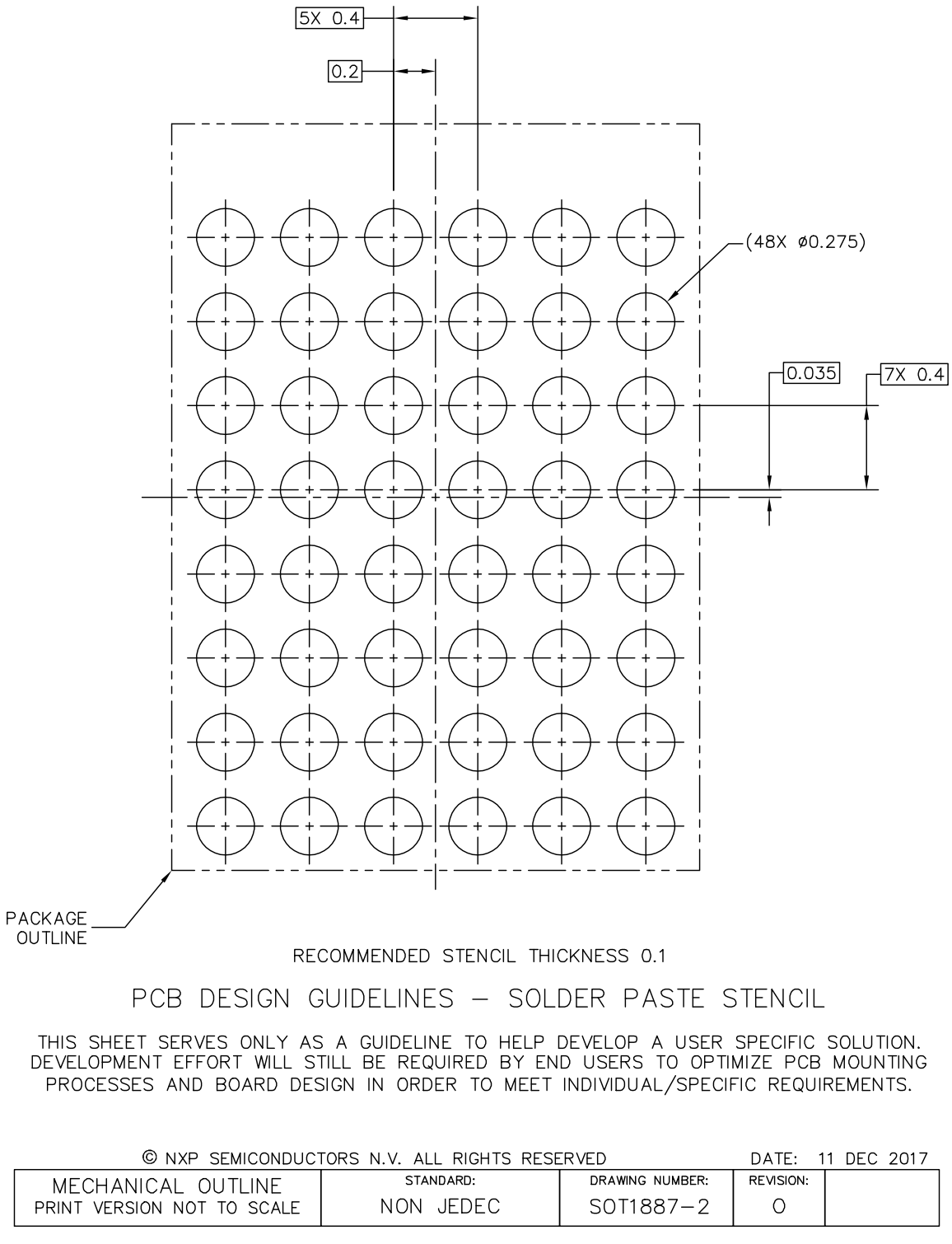

Fig. 5. Reflow soldering footprint part3 for WLCSP48 (SOT1887-2)

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5. Contents

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